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METHOD OF CUTTING CSP SUBSTRATES

ABSTRACT OF THE DISCLOSURE

A method of cutting, along the cutting streets, the CSP substrates in which CSPs are formed on each of plural rectangular regions thereof sectioned by the cutting streets arranged in a form of a lattice. The method comprises the steps of mounting plural CSP substrates on a single frame without overlapping them one upon the other, recognizing the mounting position of each of the CSP substrates on the frame and storing the mounting positions in a storage means, securing the frame mounting the plural CSP substrates onto a chuck, imaging the surface of each of the CSP substrates by a precision imaging means, and recognizing the positions of the cutting streets of each of the CSP substrates by analyzing the obtained image and storing the positions of the cutting streets of the storage means. At the time of imaging the surface of each of the CSP substrates by the precision imaging means, the chuck to which the frame is secured is positioned relatively with respect to the precision imaging means based on the stored mounting position of each of the CSP substrates on the frame.

Figure 1



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